Stanyl®

Stanyl® TC502

PA46

Thermal conductive material

Print Date: 2016-04-01

Properties	Typical Data	Unit	Test Method
Rheological properties	dry / cond		
Molding shrinkage (parallel)	0.6/*	%	ISO 294-4
Molding shrinkage (normal)	1.2/*	%	ISO 294-4
Mechanical properties	dry / cond		
Tensile modulus	9000/-	MPa	ISO 527-1/-2
Stress at break	65/-	MPa	ISO 527-1/-2
Strain at break	1.1/-	%	ISO 527-1/-2
Thermal properties	dry / cond		
Melting temperature (10°C/min)	295/*	°C	ISO 11357-1/-3
Coeff. of linear therm. expansion (parallel)	0.25/*	E-4/°C	ISO 11359-1/-2
Coeff. of linear therm. expansion (normal)	0.35/*	E-4/°C	ISO 11359-1/-2
Thermal conductivity in plane	14	W/(m K)	ASTM E1461
Thermal conductivity through plane	2.1	W/(m K)	ASTM E1461
Electrical properties	dry / cond		
Volume resistivity	10000/-	Ohm*m	IEC 60093
Other properties	dry / cond		
Humidity absorption	2/*	%	Sim. to ISO 62
Density	1420/-	kg/m³	ISO 1183

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